

Max Memory Size (dependent on memory type)

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(4M Cache, 2.40 GHz)

Intel® Core™ i3-4330TE Processor

SPECIFICATIONS

Essentials Memory Specifications Graphics Specifications Expansion Options Package Specifications Advanced Technologies Intel® Data Protection Technology Intel® Platform Protection Technology

ORDERING / SSPECS / STEPPINGS

Launch DateO3'13Processor Numberi3-4330TE# of Cores2# of Threads4Clock Speed2.4 GHzIntel® Smart Cache4 MBDMI25 GT/sInstruction Set64-bitInstruction Set ExtensionsSSE4.1/4.2, AVXEmbedded Options AvailableVesLithography.22 nmMax TDP.35 WThermal Solution SpecificationPCG 2013A	Status		Launched	
# of Cores2# of Cores2# of Threads4Clock Speed2.4 GHzIntel® Smart Cache4 MBDMI25 GT/sInstruction Set64-bitInstruction Set ExtensionsSSE4.1/4.2, AVXEmbedded Options AvailableVesLithography22 nmMax TDP.35 WThermal Solution SpecificationPCG 2013A	Launch Date		Q3'13	
# of Threads4# of Threads2.4 GHzClock Speed2.4 GHzIntel® Smart Cache4 MBDM125 GT/sInstruction Set64-bitInstruction Set ExtensionsSSE4.1/4.2, AVXEmbedded Options AvailableVesLithography22 nmMax TDP.35 WThermal Solution SpecificationPCG 2013A	Processor Number		i3-4330TE	
Clock Speed2.4 GHzIntel® Smart Cache4 MBDMI25 GT/sInstruction Set64-bitInstruction Set ExtensionsSSE4.1/4.2, AVXEmbedded Options AvailableYesLithography22 nmMax TDP35 WThermal Solution SpecificationPCG 2013A	# of Cores		2	
Intel® Smart Cache4 MBDM125 GT/sInstruction Set64-bitInstruction Set ExtensionsSSE4.1/4.2, AVXEmbedded Options AvailableYesLithography22 nmMax TDP35 WThermal Solution SpecificationPCG 2013A	# of Threads		4	
DM125 GT/sInstruction Set64-bitInstruction Set ExtensionsSSE4.1/4.2, AVXEmbedded Options AvailableYesLithography22 nmMax TDP35 WThermal Solution SpecificationPCG 2013A	Clock Speed		2.4 GHz	
Instruction Set64-bitInstruction Set ExtensionsSSE4.1/4.2, AVXEmbedded Options AvailableYesLithography22 nmMax TDP35 WThermal Solution SpecificationPCG 2013A	Intel® Smart Cache		4 MB	
Instruction Set Extensions SSE4.1/4.2, AVX Embedded Options Available Yes Lithography 22 nm Max TDP 35 W Thermal Solution Specification PCG 2013A	DMI2		5 GT/s	
Embedded Options Available Yes Lithography 22 nm Max TDP 35 W Thermal Solution Specification PCG 2013A	Instruction Set		64-bit	
Lithography 22 nm Max TDP 35 W Thermal Solution Specification PCG 2013A	Instruction Set Extensions		SSE4.1/4.2, AVX	
Max TDP 35 W Thermal Solution Specification PCG 2013A	Embedded Options Available	Q	Yes	
Thermal Solution Specification PCG 2013A	Lithography		22 nm	
	Max TDP		35 W	
Recommended Customer Price	Thermal Solution Specification		PCG 2013A	
	Recommended Customer Price			

32 GB

25.6 GB/s

2

Q

DDR3-1333/1600

Intel[®] HD Graphics 4600

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4th Generation Intel® Core™ i3 Processors Intel® Core™ i3-4300 Desktop Processor Series Products formerly Haswell



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PCN/MDDS INFORMATION

yf

USA (English)

SR180 929227: MDDS

ewsroom	Chip Shot: New Intel® Xeon® Processor Powers Real-Time Analytics
	Graphics Max Dynamic Frequency

Memory Types

of Memory Channels

Max Memory Bandwidth

ECC Memory Supported ‡

Processor Graphics ‡

Graphics Specifications

Graphics Max Dynamic Frequency	T GHZ
Intel® Quick Sync Video	Yes
Intel® InTru™ 3D Technology	Yes
# of Displays Supported ‡	3
Expansion Options	
Expansion Options PCI Express Revision	3.0
— · ·	3.0 Up to 1x16, 2x8, 1x8/2x4

Package Specifications	
Max CPU Configuration	1
T.CASE.	72°C
Package Size	37.5mm x 37.5mm
Graphics and IMC Lithography	22nm
Sockets Supported	FCLGA1150
Low Halogen Options Available	See MDDS
- Advanced Technologies	
Intel® Turbo Boost Technology [‡]	No
Intel® vPro Technology [‡]	No
Intel® Hyper-Threading Technology [‡]	Yes
Intel® Virtualization Technology (VT-x) ‡	Yes
Intel® Virtualization Technology for Directed I/O (VT- d) ±	No
Intel® VT-x with Extended Page Tables (EPT) ‡	Yes
Intel® TSX-NI	No
Intel® 64 [‡]	Yes
Idle States	Yes
Enhanced Intel SpeedStep® Technology	Yes
Thermal Monitoring Technologies	Yes
Intel® Data Protection Technology	
AES New Instructions	No
Intel® Platform Protection Technology	
Trusted Execution Technology #	No
Execute Disable Bit ‡	Yes

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"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

[‡] This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

See http://www.intel.com/content/www/us/en/architecture-and-technology/hyper-threading/hyper-threading-technology.html?wapkw=hyper+threading for more information including details on which processors support Intel® HT Technology.

Max Turbo Frequency refers to the maximum single-core processor frequency that can be achieved with Intel® Turbo Boost Technology. See www.intel.com/technology/turboboost/ for more information.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

For benchmarking data see http://www.intel.com/performance.

Intel processor numbers are not a measure of performance. Processor numbers differentiate features within each processor family, not across different processor families. See http://www.intel.com/content/www/us/en/processors/processor-numbers.html for details.

Processors that support 64-bit computing on Intel® architecture require an Intel 64 architecture-enabled BIOS.

Send us your feedback!

ARK | Intel® CoreTM i3-4330TE Processor (4M Cache, 2.40 GHz)